



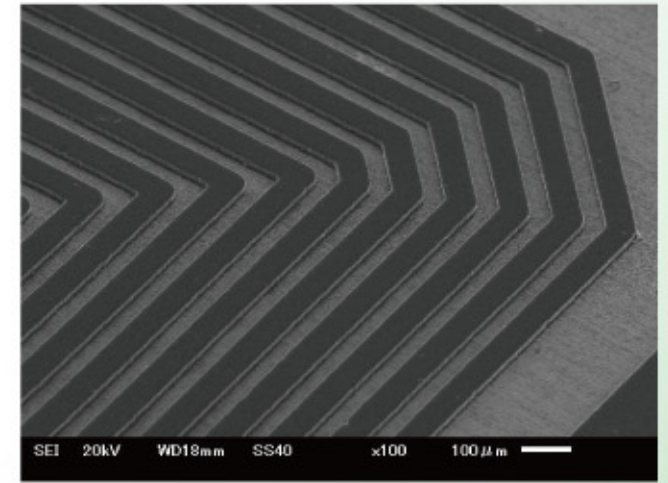
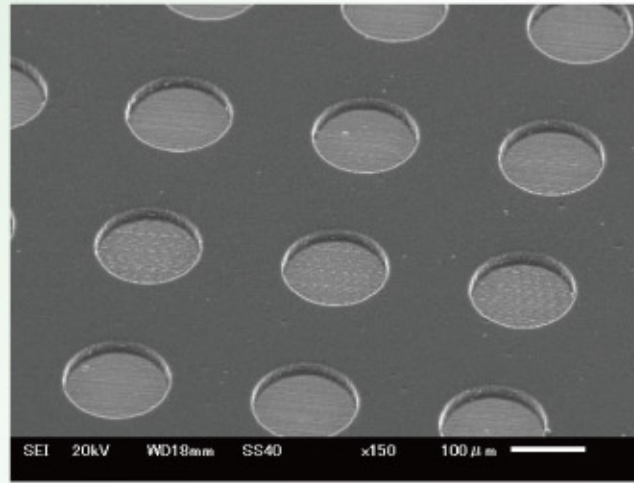
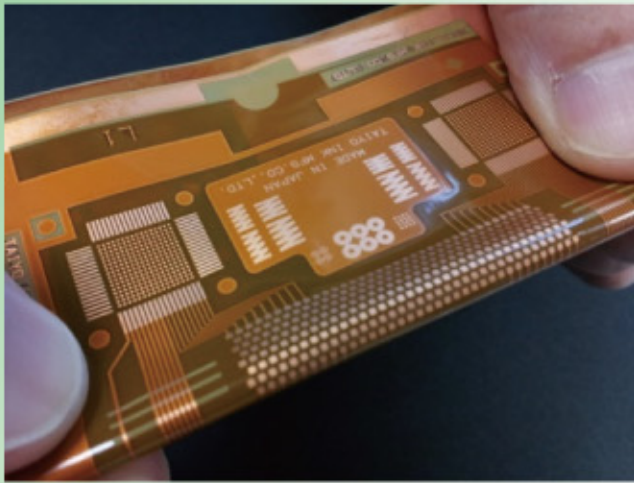
# 感光性カバーレイフィルム

Photo Imageable Cover Lay Film

## 特徴 Features

開発品  
Developing

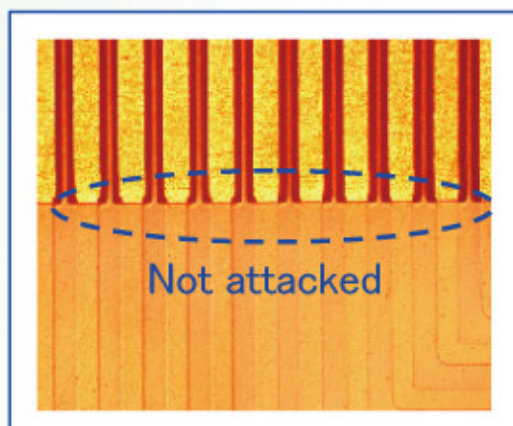
- 高解像性と高屈曲性の両立を実現した感光性ポリイミドフィルム  
Photo imageable polyimide film with coexistence of high resolution and high bendability
- 現行のプリント配線板製造ラインへの適用を実現  
Applicable to current PWB photolithography process
- 優れた耐熱性と絶縁信頼性と難燃性（VTM-0相当）を実現  
Excellent heat resistance, insulation reliability and flame resistance (VTM-0 equivalent)



## 特性 Properties

| Item                  | Condition  | Result         |
|-----------------------|--|----------------|
| Pencil hardness       | JIS 5600   | 4H             |
| Acid resistance       | 10 vol% H <sub>2</sub> SO <sub>4</sub> aq. 25 deg.C × 20 min | Pass           |
| Alkaline resistance   | 10 wt% NaOHaq. 25 deg.C × 20 min                             | Pass           |
| Heat resistance       | Solder floating 288 deg.C × 10 sec                           | Pass           |
| Au plating resistance | ENIG Ni:4 um Au:0.1um  | Pass           |
| Tg                    | TMA  | 160 deg.C      |
| Bendability           | 180deg. folding  | above 20 times |

★ENIG resistance 【Ni:4.0um Au:0.1um】



★Solder heat resistance  
【288deg.C × 10sec × 2 times】

